



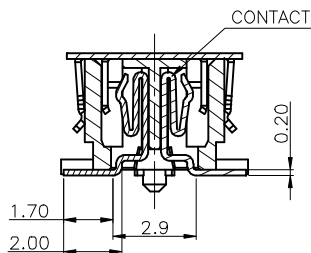
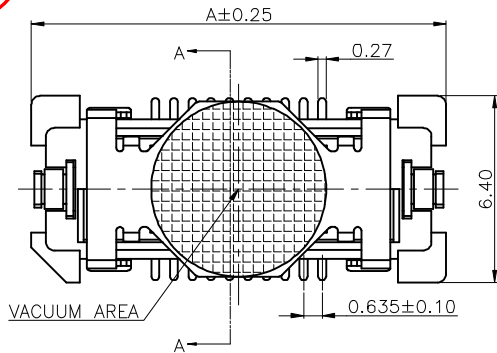
A

B

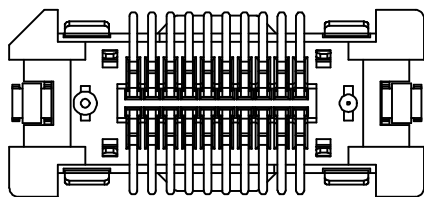
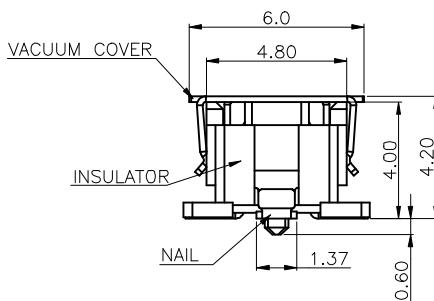
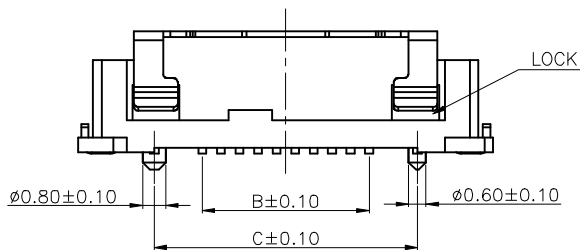
C

D

E



SECTION A-A

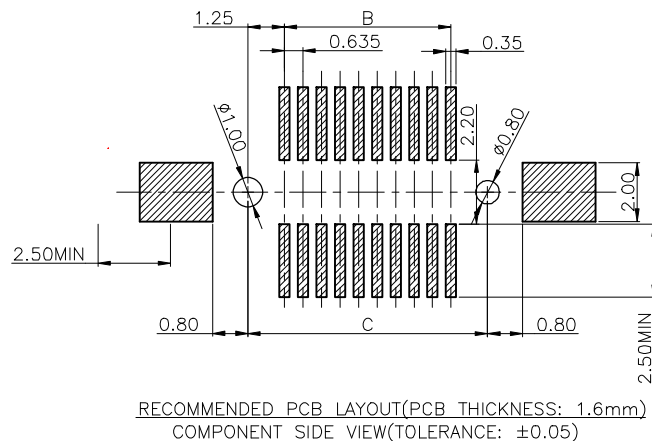


NO	53.47	50.165	58.67	160	---
	47.12	43.815	52.32	140	---
	40.77	37.465	45.97	120	---
	34.42	31.115	39.62	100	---
	31.25	27.94	36.45	90	---
YES	28.07	24.765	33.27	80	---
	24.9	21.59	30.1	70	⊗
	21.72	18.415	26.92	60	⊗
	18.55	15.24	23.75	50	⊗
	15.37	12.065	20.57	40	OK
	12.2	8.89	17.4	30	OK
	9.02	5.715	14.22	20	OK
LOCK	C	B	A	CONTACTS	AVAILABLE

- MATERIAL:
 - INSULATOR: LCP, UL 94V-0. INSULATOR COLOR: NATURE.
 - CONTACT: PHOSPHOR BRONZE, SELECTIVE GOLD (SEE ORDER INFORMATION) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 30u" MIN. NICKEL UNDERPLATED OVERALL.
 - NAIL: COPPER ALLOY, 40u" MIN TIN PLATED ON SURFACE 30u" MIN. NICKEL UNDERPLATED OVERALL.
 - VACUUM COVER: STAINLESS STEEL.
- SPECIFICATIONS:
 - CURRENT RATING: 0.5A.
 - CONTACT RESISTANCE: 40mΩ MAX.
 - INSULATION RESISTANCE: 1000MΩ MIN.
 - DIELECTRIC WITHSTANDING VOLTAGE: AC 250V PER MINUTE.
 - OPERATING TEMPERATURE: -40°C~+105°C.
- NOTES:
 - THIS COMPONENT AND ITS HOMOGENEOUS SUBCOMPONENTS ARE RoHS COMPLIANT.
 - RESISTANCE TO SOLDERING HEAT: 265°C FOR 10 SECONDS.
- SOLDER TAIL COPLANARITY 0.10mm Max.
- ORDER INFORMATION

BB213DBA2 SX- 2XX B

CONTACT PLATED:		NO. OF CONTACTS:
S1: GOLD FLASH	S5: 15u" GOLD	210: 2*10 PINS=20 PINS
S2: 3u" GOLD	S6: 30u" GOLD	215: 2*15 PINS=30 PINS
S3: 5u" GOLD	S7: 50u" GOLD	~ ~
S4: 10u" GOLD		270: 2*70 PINS=140 PINS
		280: 2*80 PINS=160 PINS



5

BO	ADD PINS OPTION ⊗	N1108020	David	Aug.26.2011
A	NEW RELEASE		Milo	Feb.15.2011
REV.	DESCRIPTION	ECN NO.	NAME	DATE

REVISIONS

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

TITLE: BOARD TO BOARD PITCH:0.635mm RECEPTACLE R/A SMT TYPE	
DWG. NO.: C-BB213DBA2SX-2XXB	DRAWN: David
PART NO.: BB213DBA2SX-2XXB	CHECKED: Karen
UNIT: mm	APPROVED: Frank
SCALE: none	RFQ NO.: Q1101033
SHEET: 1 OF 1	
DWG. SIZE: A4	
LAYER: CA059	

